

Title (en)

OPTICAL SEMICONDUCTOR HOUSING WITH TRANSPARENT CHIP AND METHOD FOR MAKING SAME

Title (de)

OPTISCHES HALBLEITERGEHÄUSE MIT TRANSPARENTEM CHIP UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

BOITIER SEMI-CONDUCTEUR OPTIQUE A PASTILLE TRANSPARENTE ET SON PROCEDE DE FABRICATION

Publication

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Application

**EP 01990608 A 20011221**

Priority

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- FR 0017264 A 20001229

Abstract (en)

[origin: WO02054497A1] The invention concerns an optical semiconductor housing and the method for making it, comprising a semiconductor component (6) whereof a rear surface is fixed on a front surface of a mounting and electrical connection support (2) and a front face comprises an optical sensor (9), means (11) electrically connecting said semiconductor component to said support, a transparent chip (12) arranged in front of said semiconductor component, which extends at least in front of said optical sensor, and encapsulating means (21) including a coating material which encloses, in front of said support, the periphery of said semiconductor component and said chip, without covering at least the central part of the front surface of said chip.

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